



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-05-12
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HZGR*KS18AA6	A	SH1A	2014-05-12
Amount	UoM	Unit type	ST ECOPACK Grade	
331.30	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	6.085X6.614X2.3	6	gull wing	
Comment	Package: TO-252 DPAK Cu Wire. MD valid also for LD1117DT18TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HZGR*KS18AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2.428	mg	supplier	die	Silicon (Si)	7440-21-3		2.372	mg	976936	7160
				supplier	metallization	Aluminium (Al)	7429-90-5		0.03	mg	12356	91
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.01	mg	4119	30
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.014	mg	5766	42
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.002	mg	824	6
Leadframe	Copper & its alloys	203.358	mg	supplier	alloy	Copper (Cu)	7440-50-8		203.093	mg	998697	613018
				supplier	alloy	Iron (Fe)	7439-89-6		0.094	mg	462	284
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.171	mg	841	516
Soft solder	Other organic materials	2.237	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.136	mg	954850	6447
				supplier	solder	Silver (Ag)	7440-22-4		0.056	mg	25034	169
				supplier	solder	Tin (Sn)	7440-31-5		0.045	mg	20116	136
Bonding wire	Other inorganic materials	0.155	mg	supplier	wire	Copper (Cu)	7440-50-8		0.155	mg	1000000	468
				supplier	mold compound	Epoxy Resin	Proprietary		3.662	mg	29997	11053
				supplier	mold compound	2,2'-(1,3,3',5,5'-tetramethyl-4,4'-biphenyl)-4,4'	EC 413-900-7		4.883	mg	39999	14739
				supplier	mold compound	phenol resin	Proprietary		6.104	mg	50001	18424
				supplier	mold compound	Silica, vitreous	60676-86-0		106.818	mg	875005	322421
encapsulation	Other organic materials	122.077	mg	supplier	mold compound	Carbon black	1333-86-4		0.61	mg	4997	1841
				supplier	mold compound	Carbon black	1333-86-4		0.61	mg	4997	1841
connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3154